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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

- 1) JONG-JIN PARK
- 2) TAE-YONG NOH
- 3) MYEONG-SUK KIM
- 4) SUNG-HUN LEE
- 5) EUN-JEONG JEONG
- 6) DONG-WOO SHIN
- 7) LYONG-SUN PU

Additional name(s) of conveying party(ies) attached?  Yes  No

2. Name and address of receiving party(ies):

**SAMSUNG SDI CO.,LTD.,**  
*a corporation organized under the laws of  
the Republic of Korea*  
575 Shin-dong,  
Yeongtong-gu, Suwon-si, Gyeonggi-do  
Republic of KOREA

Additional name(s) & addresses attached?  Yes  No

3. Nature of conveyance

- Assignment  Merger
- Security Agreement  Change of Name
- Other

Execution Date: 16 June 2006

4. Application number(s) or Patent number(s):

If this document is being filed together with a new application, the execution of the application is: 16 June 2006

A. Patent Application No.(s)  
to be assigned

B. Patent No.(s)

Additional number(s) attached?  Yes  No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Robert E. Bushnell  
Attorney at Law  
Suite 300, 1522 "K" Street, N.W.  
Washington, D.C. 20005-1202  
(202) 408-9040

6. Total Number of applications and patents involved: ONE

7. Total fee (37 CFR § 3.41) . . . . . \$ U.S. \$40.00  
 Enclosed (**Check# 50958**)  
 Authorized to be charged to deposit account

8. Deposit Account Number:

(Attach duplicate copy of this page if paying by deposit account)

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9. Statement and Signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

ROBERT E. BUSHNELL  
Name of Person Signing

*Robert E. Bushnell*  
Signature

16 June 2006  
Date

Total number of pages including cover sheet: THREE

OMB No. 0651-0011 (exp. 4/94)

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DOCKET No. P58006

# ASSIGNMENT (Page One of Two)

AS A BELOW NAMED INVENTOR, I, and each of us, individually hereby declare that: IN CONSIDERATION of the sum of TEN (\$10.00) dollars or the equivalent thereof, and other good and valuable consideration, the receipt of which from the hereinafter named Assignee is hereby acknowledged, I do hereby sell, assign and forever grant and convey unto:

**ASSIGNEE: SAMSUNG SDI CO., LTD.,**  
*a corporation organized under the laws of the Republic of Korea.*

**ADDRESS: 575 Shin-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, Republic of KOREA**

Who is my Assignee, and in the successors and assigns of my Assignee, all my right, title and interest, in and for the United States of America and all other countries, including all rights of priority, in and to the invention entitled:

## TITLE: METHOD OF FORMING ORGANIC SEMICONDUCTOR LAYER PATTERN

invented by me (if only one inventor is named below) or us (if more than one inventor is named below) and described in an application for a United States patent the specification of which is either attached hereto or otherwise accompanies this Assignment, or is more particularly identified as:

executed on even date herewith, or

Serial No. \_\_\_\_\_, filed in the U.S. Patent & Trademark Office on \_\_\_\_\_, or

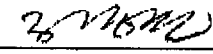

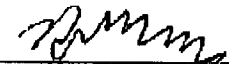
executed on \_\_\_\_\_

and in and to all United States patents which may be granted thereon and therefore, and in and to all certificates of corrections, divisions, continuations, continuations-in-part, reissued and re-examined patents, and to any extensions thereof, said interest being the entire ownership of the patent when granted, to be held and enjoyed by said SAMSUNG SDI CO., LTD., my Assignee, its successors, assigns or other legal representatives, to the full end of the term, terms, or any extension or renewal thereof, for which said patent or patents may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment, sale and conveyance had not been made;

AND I hereby covenant and agree to sign and execute, without receiving any money or other consideration, any further documents or instruments which may from time-to-time be either necessary, lawful, proper or requested by the Assignee, in the prosecution of the above-named application or in the preparation and prosecution of all substitute applications, certificate of correction, division, continuation, continuation-in-part, reissue, re-examination, in any amendment, extension, or interference proceeding, whether administrative or judicial, or otherwise, to secure the title hereto in said Assignee, together with the right of priority under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreement or treaty to which the United States of America adheres;

AND I do hereby authorize and request the Commissioner of Patent & Trademarks to issue said Patent or Patents to the Assignee, and I hereby appoint as my, or our attorney, and authorize and request R. E. Bushnell, Reg. No. 27,774, to insert on this Assignment any further identification or to complete such identification which may be either necessary or desirable in order to comply the rules of the United States Patent & Trademark Office for recordation of this document.

IN WITNESS WHEREOF, I and we have set our hands and seals on the dates written beside my and our respective names:

<u>INVENTOR(s)</u>	<u>Date Signed</u>	<u>Witness(es)</u>
1) <u></u> (Seal) JONG-JIN PARK	<u>16/ Jun / 2006</u>	
2) <u></u> (Seal) TAE-YONG NOH	<u>16/ June / 2006</u>	
3) <u></u> (Seal) MYEONG-SUK KIM	<u>16/ Jun / 2006</u>	

Additional inventors are being named on separately numbered sheets attached hereto.

DOCKET No. P58006

**ASSIGNMENT** (Page Two of Two)

4) *Sung-hun Lee* (Seal)  
SUNG-HUN LEE

16/June/2006

5) *[Signature]* (Seal)  
EUN-JEONG JEONG

16/June/2006

6) *[Signature]* (Seal)  
DONG-WOO SHIN

16/June/2006

7) *[Signature]* (Seal)  
LYONG-SUN PU

16/June/2006

8) \_\_\_\_\_ (Seal)

\_\_\_\_\_